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(3) s

Schematic diagram

NCE6075K YY WW

D

Marking and pin Assignment

TO-252-2L top view

NCE

(1) GO

NCE6075K

NCE N-Channel Enhancement Mode Power MOSFET



The NCE6075K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

GENERAL FEATURES

- $V_{DS} = 60V, I_D = 75A$ $R_{DS(ON)} < 11.5m\Omega @ V_{GS} = 10V$ (Typ:9.1m Ω)
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

100% UIS TESTED!

100% ΔVds TESTED!



Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6075K	NCE6075K	TO-252-2L	-	-	-

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	75	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	50	А
Pulsed Drain Current	I _{DM}	300	А
Maximum Power Dissipation	PD	110	W
Derating factor		0.73	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	450	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	R _{θJC}	1.36	°C/W	
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Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60	68	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =30A	-	9.1	11.5	mΩ
Forward Transconductance	g fs	$V_{DS}=25V,I_{D}=30A$	20	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C _{lss}		-	2350	-	PF
Output Capacitance	C _{oss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz	-	237	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ	-	205	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	16	-	nS
Turn-on Rise Time	tr	V_{DD} =30V, I_D =2A, R_L =15 Ω	-	10	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =2.5 Ω	-	45	-	nS
Turn-Off Fall Time	t _f		-	12	-	nS
Total Gate Charge	Qg	V/ 20V/L 20A	-	50	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=30V, I_{D}=30A,$	-	12	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	16	-	nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =30A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	75	А
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =75A	-	28		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)	-	49		nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production

5. EAS condition: Tj=25 $^\circ \!\! C$,V_DD=30V,V_G=10V,L=0.5mH,Rg=25\Omega

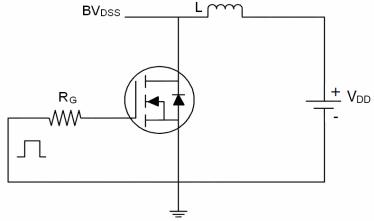




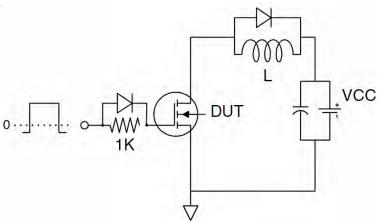


Test circuit

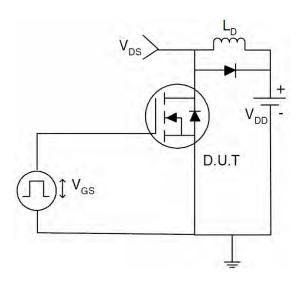
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:

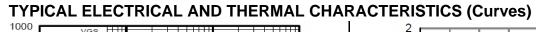


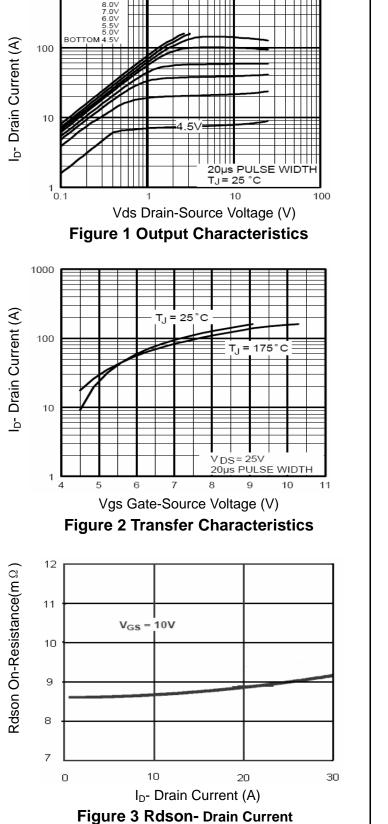


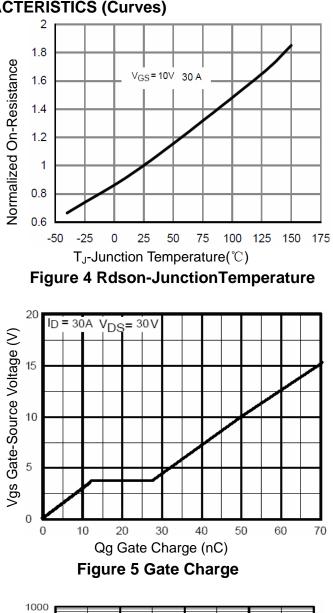
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NCE6075K







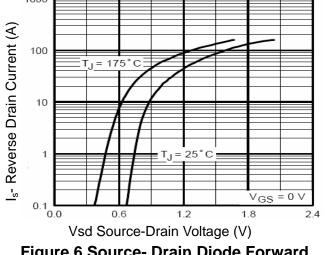


Figure 6 Source- Drain Diode Forward



Pb Free Product

100

V_{DS}=V_{GS} I_D=250µA

100

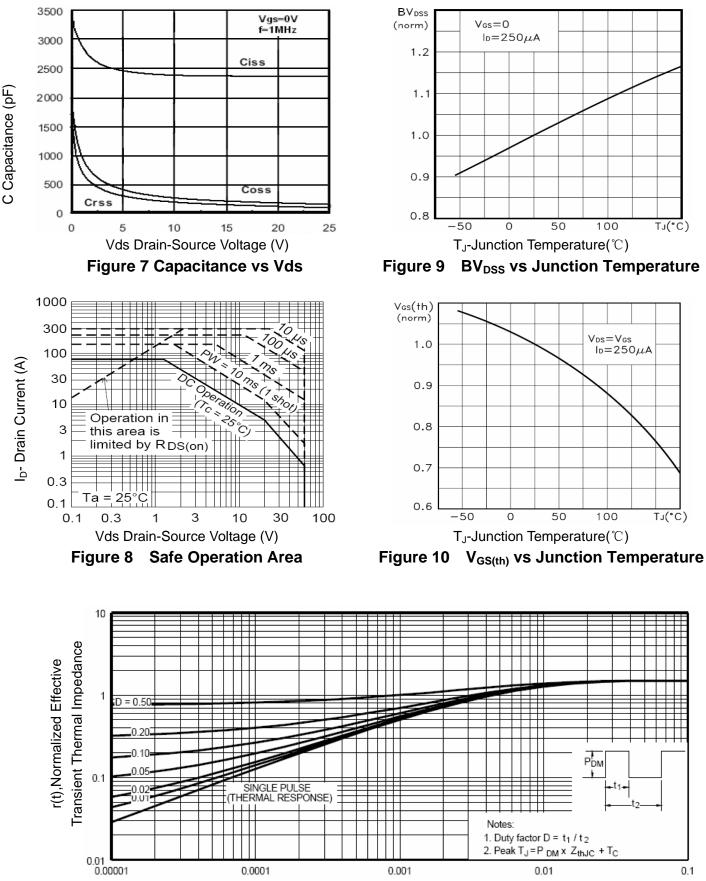
PDM

TJ(°C)

(°C)

0.1

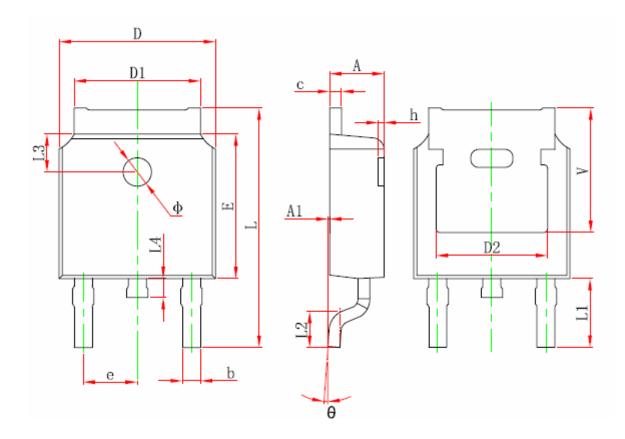
NCE6075K



Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance







Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	REF.	0.190 REF.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	REF.	0.114	REF.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	REF.	0.063	REF.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	REF.	0.211	REF.	







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